

SJ

**INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

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**Solder preform for insulated gate bipolar transistors (IGBT)
(English Translation)**

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What this standard covers

This standard specifies the terms and definitions, chemical composition, technical requirements, test methods, inspection rules, and requirements for marking, packaging, transportation, and storage of solder pads used in Insulated Gate Bipolar Transistors (IGBTs). This document applies to solder pads used in the IGBT manufacturing process.

Document data

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